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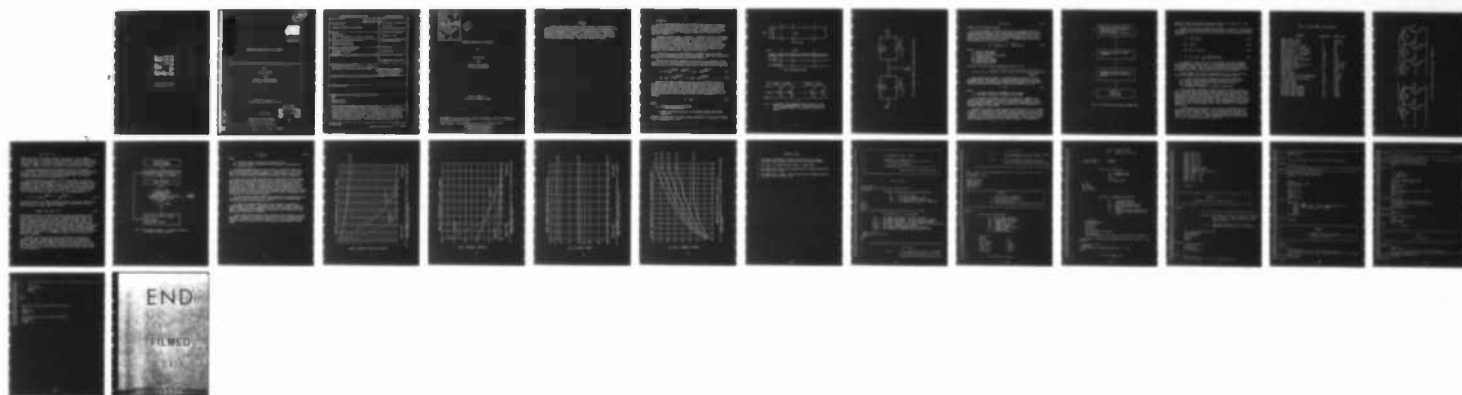
NUMERICAL MODELING OF THE MOSBJT(U) HAWAII UNIV AT  
MANOA HONOLULU DEPT OF ELECTRICAL ENGINEERING  
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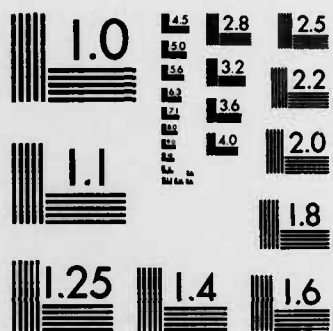
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# NUMERICAL MODELING OF THE MOSBJT

by

David Okada

and

James W. Holm-Kennedy  
Principal Investigator

ONR Final Report II  
Contract No. N-0014-76-C-1081

July 1983

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# NUMERICAL MODELING OF THE MOSBJT\*

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and

James W. Holm-Kennedy,  
Principal Investigator

ONR Final Report II  
Contract No. N-0014-76-C-1081

\*The MOSBJT was proposed by Prof. James W. Holm-Kennedy, Electrical Engineering Department, University of Hawaii.

Patent pending. Work supported in part by the University of Hawaii.

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# ABSTRACT

A totally merged MOSFET and BJT has been proposed. The device exhibits complicated non-linear characteristics under certain operating conditions. Due to the distributed character of this novel merged device, a straightforward lumped device approach is not adequate. A distributed model is proposed and analyzed using numerical techniques. The active device area is shown to be affected by bias and contributes to the non-linear character of the characteristics under suitable conditions. Several gate shapes are treated.

## 1. Introduction

A novel merged MOSFET/BJT device (the MOSBJT) was previously described [1]. The device is fully merged which results in a distributed behavior. The MOSFET channel can be used as an emitter or as a collector. In order to analyze the device, a distributed FET BJT model must be used. Approximate analytical models have been treated [2] and will be reported elsewhere and is similar to that described in Report III.

The MOSBJT numerical model is based upon an equivalent circuit for the MOSBJT. The construction of the equivalent circuit is as follows: First the distributed bipolar injection into the MOSBJT channel is modeled by dividing the device length-wise into many equal sections (refer to Fig. 3.1a, b). Each section is then represented by a n-channel metal oxide semiconductor field effect transistor (MOSFET) connected to a npn bipolar junction transistor (BJT) resulting in the equivalent circuit shown in Fig. 3.1c. Built into this circuit model is the assumption that minority carrier transport occurs vertically.

The npn BJTs and the n-channel MOSFETs in the MOSBJT equivalent circuit (Fig. 3.1c) are represented by their classical DC models. These are the Ebers-Moll BJT model [3] and the distributed analysis MOSFET model [4].

The Ebers-Moll BJT model represents the npn BJT with the equivalent circuit shown in Fig. 3.2. From the equivalent circuit the following expressions for the collector current ( $I'_C$ ) and the base current ( $I'_B$ ) for the transistor are determined.

$$I'_C = \alpha_F I_{ES} [e^{qV_{BE}/KT} - e^{qV_{BC}/KT}] - I_{CS} (1 - \alpha_R) [e^{qV_{BC}/KT} - 1] \quad (3.1)$$

$$I'_B = I_{ES} (1 - \alpha_F) [e^{qV_{BE}/KT} - 1] + I_{CS} (1 - \alpha_R) [e^{qV_{BC}/KT} - 1] \quad (3.2)$$

The Ebers-Moll model parameters ( $\alpha_F, \alpha_R, I_{ES}, I_{CS}$ ) for the BJT elements in the MOSBJT circuit model are extracted from the experimental data of a typical rectangular MOSBJT operating with the entire channel active. The magnitude of the BJT collector current for a particular section ( $I_{Cx}$ ) is proportional to the collector area of that section. The proportionality constant is determined by normalizing the area of each section to the total collector (channel) area. This factor is then used to scale the total collector current expressed by Eq. (3.1) yielding:

$$I_{Cx} = K_x I'_C \quad (3.3)$$

where

$$K_x = \frac{\text{collector area of the } x^{\text{th}} \text{ section}}{\text{total collector area}}$$

$x \equiv$  integer specifying the section of the numerical MOSBJT model being referred to

Similarly an expression for the base current contribution of a particular section,  $x$  can be expressed by Eq. (3.4).



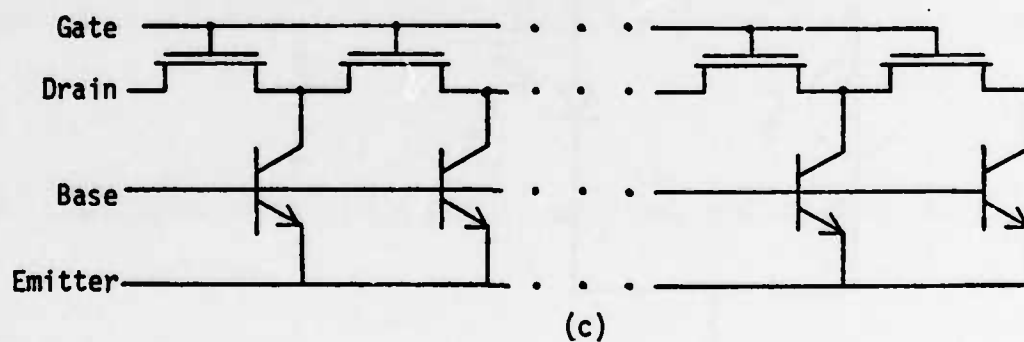
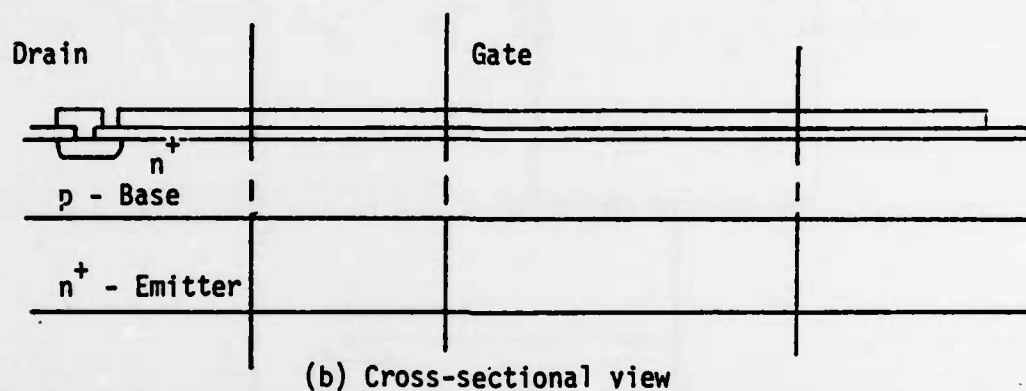
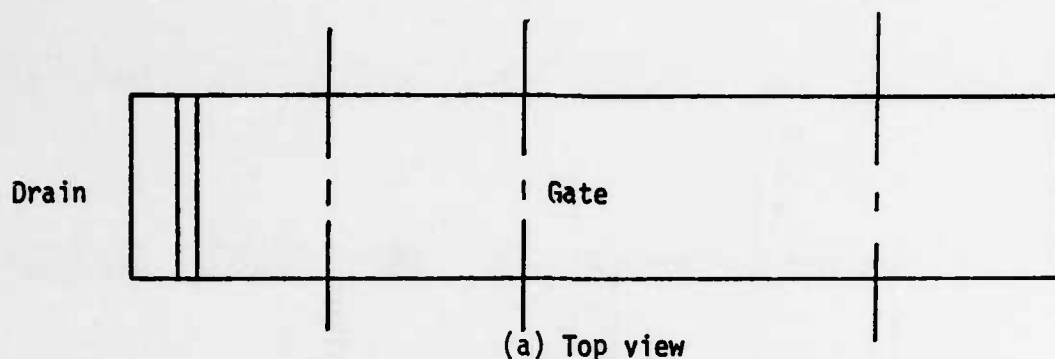


Fig. 3.1 Development of the MOSBJT equivalent circuit. (a) Top view of a rectangular MOSBJT. (b) Cross-sectional view of a rectangular MOSBJT. (c) Equivalent circuit of the MOSBJT.



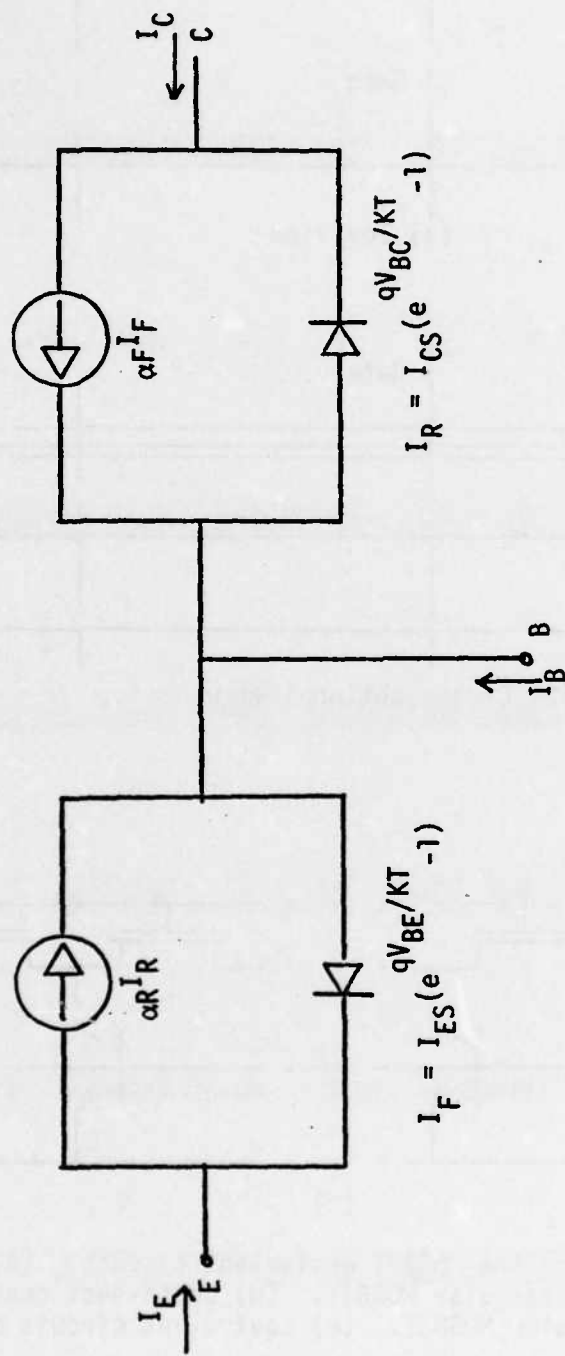


Fig. 3.2 Ebers-Moll model of a npn bipolar junction transistor

$$I_{Bx} = K_x I_B' \quad (3.4)$$

where  $K_x$  and  $x$  are defined as above.

The n-channel MOSFETs are modeled with the distributed MOSFET model and the gradual channel approximation [3]. Incorporated into the MOSFET model are the assumptions that the channel voltage can be approximated by a half of the sum of the source and drain voltages ( $\frac{1}{2}(V_S + V_D)$ ) and that the channel length is much greater than the depletion region at the drain. The MOSFET model yields the following expression for the drain current ( $I_D$ ).

$$I_D = \mu_n \frac{W}{L} C_{ox}' (V_G - V_T - (\frac{V_D - V_S}{2}))(V_D - V_S) \quad (3.5)$$

where

- $W \equiv$  width of the channel
- $L \equiv$  length of the channel
- $\mu_n \equiv$  electron mobility in the channel
- $V_T \equiv$  threshold voltage
- $V_D \equiv$  applied drain voltage
- $V_S \equiv$  applied source voltage
- $V_G \equiv$  applied gate voltage

Solving Eq. (3.5) for the drain voltage ( $V_D$ ) yields Eq. (3.6).

$$V_D = V_S + V_G - V_T - \sqrt{(V_S + V_G - V_T)^2 - (2(V_G - V_T) + V_S^2 + \frac{2(V_G - V_T)I_D L}{\mu_n W C_{ox}'})} \quad (3.6)$$

The n-channel MOSFET elements in the MOSBJT circuit model (Fig. 3.1c) are represented by Eqs. (3.5) and (3.6). Since each MOSFET represents a section of the MOSBJT channel, the length of each MOSFET should be equal to the total MOSBJT channel length divided by the number of sections as expressed by Eq. (3.7).

$$L' = L/N \quad (3.7)$$

where

- $L' \equiv$  the channel length for the MOSFET circuit elements
- $N \equiv$  the number of sections in the MOSBJT circuit model

For a rectangular gate MOSBJT the width of the gate of the MOSFET circuit element will simply be equal to the width of the MOSBJT gate. MOSBJT's with non-rectangular gate geometries are easily simulated by representing each section with a rectangular MOSFET of length  $L/N$  and width equal to the average width of the MOSBJT channel in that section.

The computer algorithm, listed in Appendix A and outlined in Fig. 3.3, consists of 4 modules. The function of these modules, labeled A through D, are as follows: In Module A, the MOSBJT material properties, device characteristics, geometry, and operating bias are defined and various required parameters calculated. The purpose of module B is to determine the extent of channel cut-off. Next in module C the spatial dependence of voltage and current along the channel is determined and

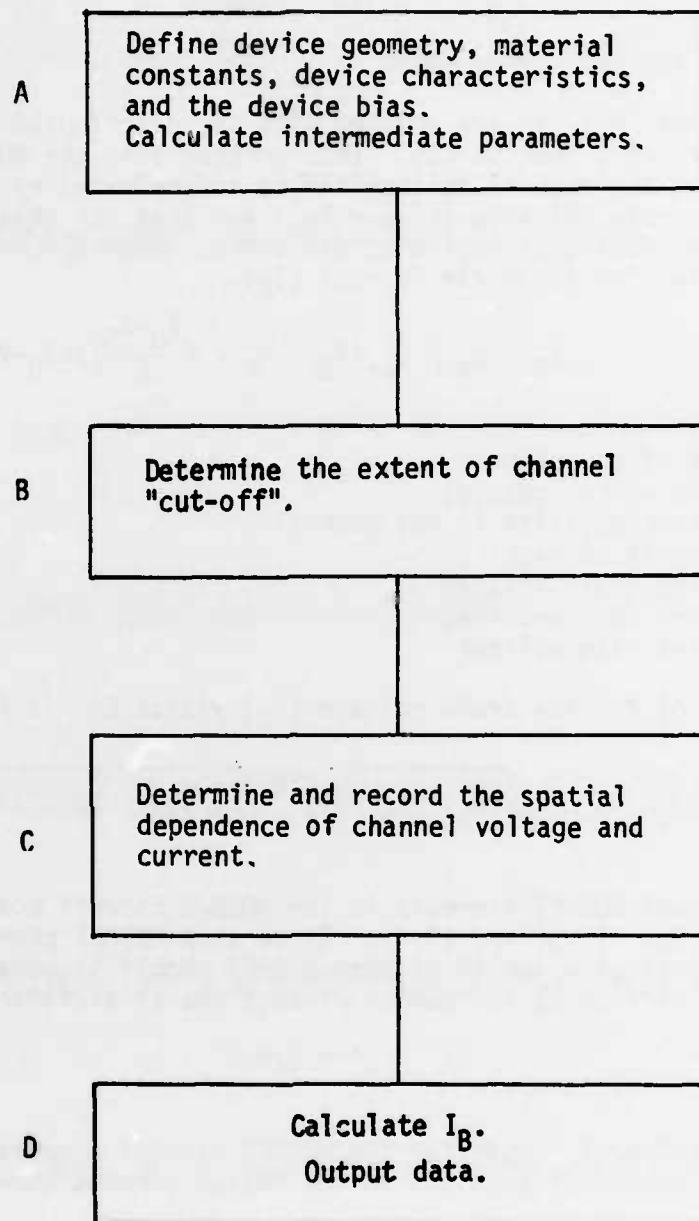


Fig. 3.3 Flow chart of the numerical MOSBJT model

recorded. Finally in module D the base current ( $I_B$ ) is calculated and its value along with the rest of the data is printed or plotted.

In module A, the numerical MOSBJT model parameters are defined. These parameters are listed in Table 3.1 along with their typical values. Values for  $\phi_p$ ,  $C'_{ox}$ ,  $V_{FB}$ ,  $V_T$  are determined by evaluating the following expressions derived from conventional MOS theory [3].

$$\phi_p = -\frac{KT}{q} \ln(N_a/N_i) \quad (3.8)$$

$$C'_{ox} = \epsilon_{ox}/T_{ox} \quad (3.9)$$

$$V_{FB} = \phi_M - \phi_s - Q_{ss}/C'_{ox} \quad (3.10)$$

$$V_T = V_{fb} + 2|\phi_p| + \frac{1}{C'_{ox}} \sqrt{2\epsilon_{sq}N_a(2|\phi_p| - V_{BE})} \quad (3.11)$$

A substantial portion of the iterative algorithm of the numerical MOSBJT model is contained in modules B and C. In these modules the spatial dependence of the MOSBJT's channel voltage and current are determined for a given device bias ( $V_{DE}$ ,  $V_{BE}$ , and  $V_G$ ). Once the channel voltage and current profiles are known the terminal drain current ( $I_D$ ) and base current ( $I_B$ ) can be determined.

The basic MOSBJT circuit model is shown again in Fig. 3.4 with the various nodes, node voltages, and currents labeled with the following notation:

- $X \equiv$  integer indicating the  $X^{th}$  section of the numerical MOSBJT model
- $I_{MX} \equiv$  current flowing through the MOSFET located in the  $X^{th}$  section
- $I_{CX} \equiv$  collector current for the BJT located in the  $X^{th}$  section
- $V_X \equiv$  voltage at the  $X^{th}$  node
- $N \equiv$  the number of sections for the numerical MOSBJT model

A simple approach to determine the node voltages and currents would be to start at the drain where the voltage is known and then calculate the node voltage and current moving from node to node in the direction away from the drain. This approach does not yield a solution because finding  $V_N$  (the voltage at the node adjacent to the drain) requires that  $I_{MN}$  be known.  $I_{MN}$  is equal to the sum of the BJT collector currents at all other nodes. These collector currents are in turn dependent on their respective node voltages. The interdependence of node voltages and currents lead to the development of an iterative approach for the numerical MOSBJT model.

In this approach an initial guess is first made of the voltage ( $V_1$ ) at the node furthest from the drain (node 1). Next,  $I_C$  can be solved for using the expression for the collector current of a BJT obtained from the Ebers-Moll BJT model (Eq. (3.3)). The current flowing through the MOSFET interconnecting nodes 1 and 2, ( $I_M$ ) is equal to  $I_{C1}$ . A general expression relating the node currents, (Eq. (3.12)) is derived with Kirchoff's current law.

Table 3.1 Typical MOSBJT Device Parameters

Parameter	Nomenclature	Typical Value
MOSBJT channel length	$L$	$3.68\text{E-}3 \text{ M}$
MOSBJT channel width	$W$	$2.96\text{E-}3 \text{ M}$
Number of sections in model	$N$	100
Gate voltage w.r.t. the emitter	$V_G$	30V
Drain voltage w.r.t. the emitter	$V_{DE}$	20V
Base voltage w.r.t. the emitter	$V_{BE}$	0.38V
Metal work function (Al)	$\phi_M$	4.1ev
Semiconductor work function (Si)	$\phi_S$	4.9ev
Oxide permittivity	$\epsilon_{ox}$	$3.45\text{E-}11 \text{ F/M}$
Semiconductor permittivity (Si)	$\epsilon_S$	$1.04\text{E-}10 \text{ F/M}$
Semiconductor doping	$N_a$	$1.5\text{E}16 \text{ cm}^{-3}$
Temperature	$T$	300°K
Oxide thickness	$T_{ox}$	$1.2\text{E-}7 \text{ M}$
Electric potential of the semiconductor	$\phi_p$	-0.358V.
Oxide capacitance per unit area	$C_{ox}$	$2.88\text{E-}4 \text{ F}$
Flatband voltage	$V_{FB}$	-1.08V
Threshold voltage	$V_T$	1.72V
Ebers-Moll model parameter	$\alpha_F$	0.9615
Ebers-Moll model parameter	$\alpha_R$	0.9975
Ebers-Moll model parameter	$I_{ES}$	$1.04\text{E-}8$
Ebers-Moll model parameter	$I_{CS}$	$1.002\text{E-}8$

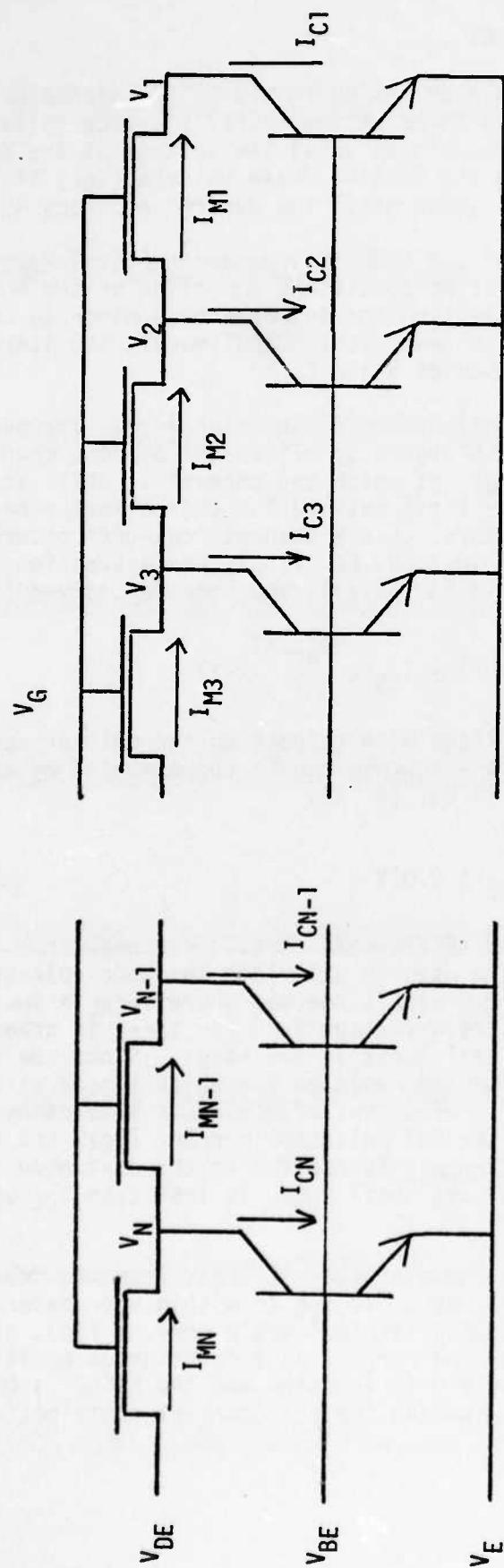


Fig. 3.4 Equivalent circuit for the numerical MOSBJT model

$$I_{MX} = I_{MX-1} + I_{CX} \quad (3.12)$$

Knowing  $V_1$  and  $I_M$ ,  $V_2$  is then calculated, using Eq. (3.6) in which a MOSFET's drain voltage ( $V_{X+1}$ ) is expressed in terms of the MOSFET's source voltage ( $V_X$ ) and drain current ( $I_{MX}$ ). This process continues until the voltage at the drain ( $V_{DCAL}$ ) is found. If  $V_{DCAL}$  is not equal to the applied drain voltage ( $V_{DE}$ ) iterative adjustments are made to the initial guess until the desired accuracy is achieved.

From the basic understanding of the MOSBJT's operation [Final Report I] it is known that under certain operating conditions a portion of the MOSBJT channel may be "cut-off" - incapable of collecting the injected base minority carriers. To incorporate channel "cut-off" into the numerical MOSBJT model, the iterative algorithm is partitioned into two modules B and C.

In module B the extent of channel "cut-off" is determined. The algorithm contained in module B is diagramed in Fig. 3.5. First the minimum channel voltage with respect to the emitter ( $V_{CHEMIN}$ ), at which the channel is still active as a collector is found. This is done by first solving for the collector-base voltage ( $V_{BC}$ ) at which channel "cut-off" occurs. Since channel "cut-off" occurs when the BJT collector current ( $I_{CX}$ ) is equal to zero, Eq. (3.3), the expression for  $I_{CX}$  can be set equal to zero, as shown in Eq. (3.13), and then  $V_{BC}$  solved for.

$$0 = I_{CX} = K_X F I_{ES} (e^{qV_{BE}/KT} - 1) - I_{CS} (e^{qV_{BC}'/KT} - 1) \quad (3.13)$$

The sum  $V_{BC}' + V_{BE}$  is the channel voltage with respect to the emitter necessary for channel "cut-off" to occur. Therefore  $V_{CHEMIN}$  can be approximated by adding a small voltage to this sum as shown in Eq. (3.14).

$$V_{CHEMIN} = V_{BC}' + V_{BE} + 0.01V \quad (3.14)$$

After  $V_{CHEMIN}$  is found it is applied to the node located furthest from the drain. Equation (3.3), (3.6), and (3.12) are used to calculate the node voltages and currents along the channel until the drain is reached where  $V_{DCAL} = V_{N+1}$ . Then  $V_{DCAL}$  is compared with the applied drain voltage  $V_{DE}$ . If  $V_{DCAL}$  is greater than  $V_{DE}$  the implication is that the initial guess is too large. Since the voltage applied to node 1 was  $V_{CHEMIN}$  (the minimum voltage for which a node will be "active"), node 1 must be biased into "cut-off." The "cut-off" node is modeled by setting the node voltage ( $V_1$ ) to ( $V_{BC} + V_{BE}$ ) and the BJT collector current ( $I_{C1}$ ) and the MOSFET current ( $I_{M1}$ ) equal to zero. Then  $V_{CHEMIN}$  is applied to the next node (node 2) and the process is repeated. This continues until  $V_{DCAL}$  is less than  $V_{DE}$  upon which module C is executed.

In module C the voltage at the "active" node furthest from the drain is adjusted until  $V_{DCAL}$  is approximately equal to  $V_{DE}$  to within a predetermined accuracy. When this occurs the MOSBJT's terminal drain current ( $I_D$ ), given by  $I_{MN}$  and the MOSBJT's channel voltage and current as a function of position along the channel are recorded. Next module D is executed and the MOSBJT's base current ( $I_B$ ) is calculated.  $I_B$  is found by summing the base current contributions of each section as shown below.



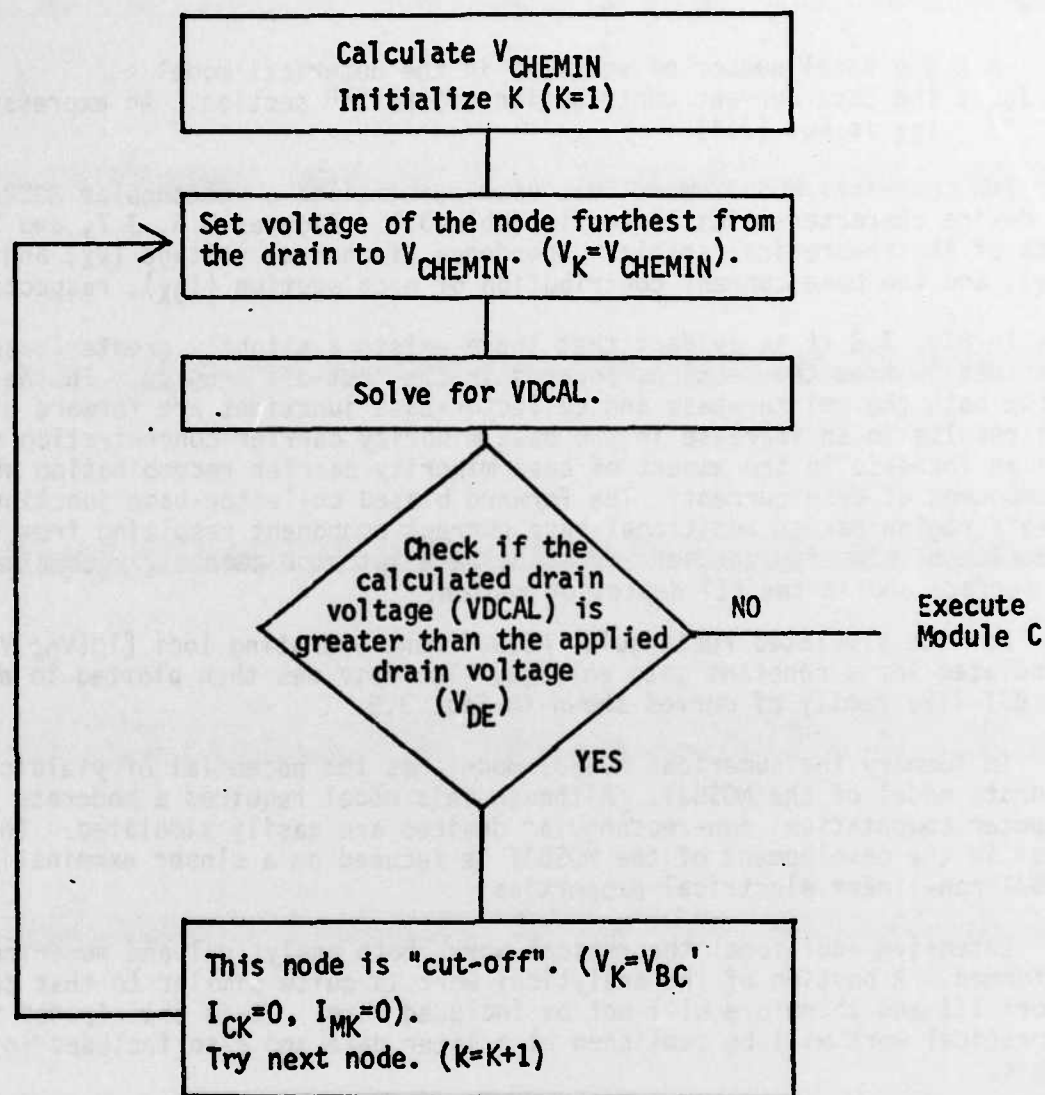


Fig. 3.5 Flow chart of module B. This module determines the extent of channel "cut-off".

$$I_B = \sum_{x=1}^N I_{BX} \quad (3.15)$$

where

$N \equiv$  the total number of sections in the numerical model  
 $I_{BX} \equiv$  the base current contribution of the  $X^{\text{th}}$  section. An expression for  $I_{BX}$  is Eq. (3.4).

The numerical MOSBJT model was used to simulate a rectangular MOSBJT with the device characteristics listed in Table 3.1. Figures 3.6, 3.7, and 3.8 are plots of the theoretical spatial dependence of channel voltage ( $V_X$ ) and current ( $I_{MX}$ ), and the base current contribution of each section ( $I_{BX}$ ), respectively.

In Fig. 3.8 it is evident that there exists a slightly greater base current contribution from the sections located in the "cut-off" region. In the "cut-off" region both the emitter-base and collector-base junctions are forward biased. This results in an increase in the base minority carrier concentration and therefore an increase in the amount of base minority carrier recombination which is a component of base current. The forward biased collector-base junction of the cut-off region has an additional base current component resulting from the "reverse" injection of minority carriers from the base into the channel, recombination at the MOS surface and in the FET depletion region.

For the simulated rectangular MOSBJT many operating loci [ $I_D(V_{DE}, V_G, I_B)$ ] were calculated for a constant gate voltage. The data was then plotted to produce the BJT-like family of curves shown in Fig. 3.9.

In summary the numerical MOSBJT model has the potential of yielding an accurate model of the MOSBJT. Although this model requires a moderate amount of computer computation, non-rectangular devices are easily simulated. The current level in the development of the MOSBJT is focused on a closer examination of the MOSBJT non-linear electrical properties.

Extensive additional theoretical work, both analytical and numerical has been performed. A portion of the analytical work is quite similar to that described in Report III and therefore will not be included here. It is anticipated that this theoretical work will be published at a later date and also included in a Ph.D. Thesis.

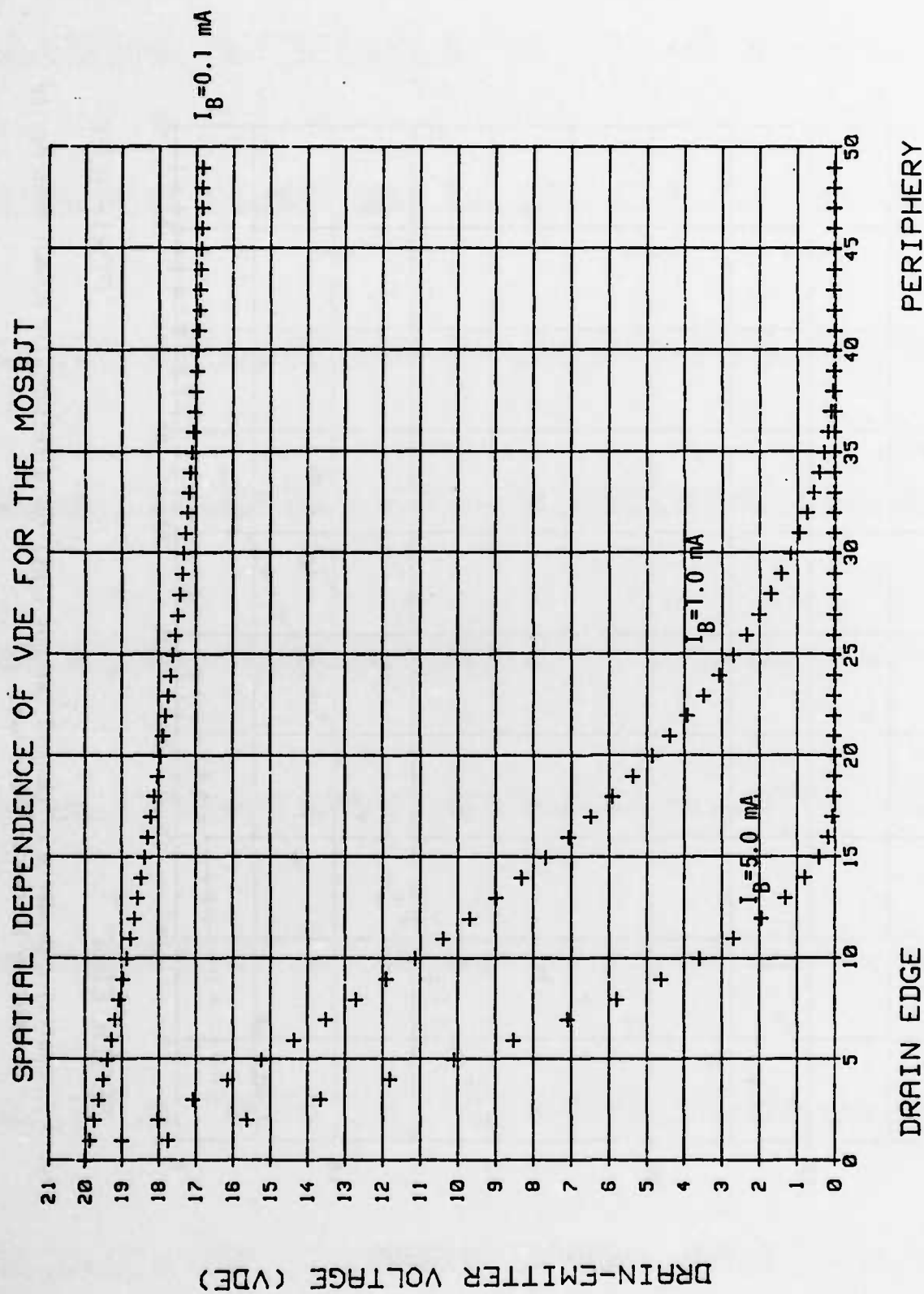


Fig. 3.6 Spatial dependence of channel-emitter voltage ( $V_X$ ) for a rectangular MOSBJT with device parameters listed in Tabel 3.1.

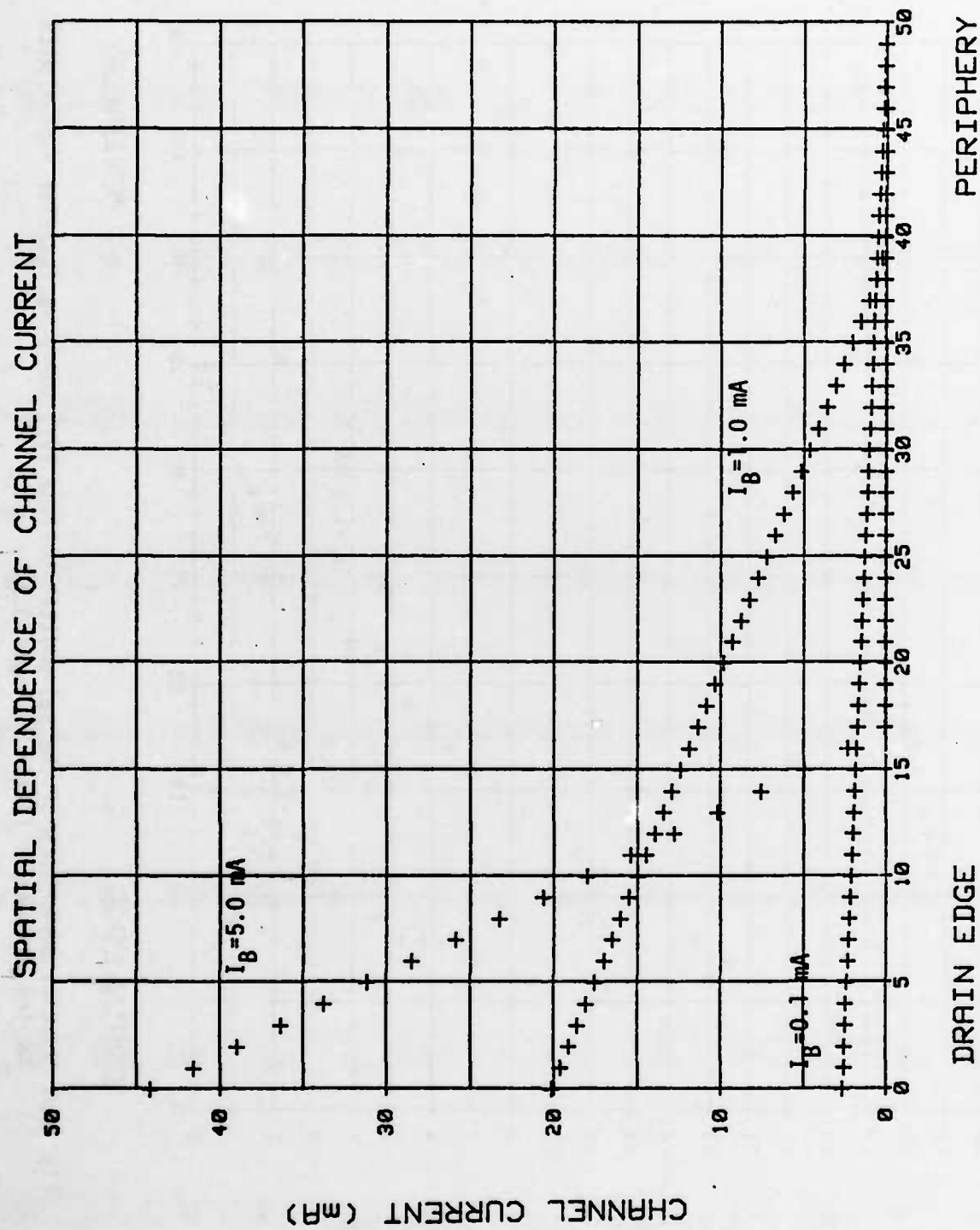
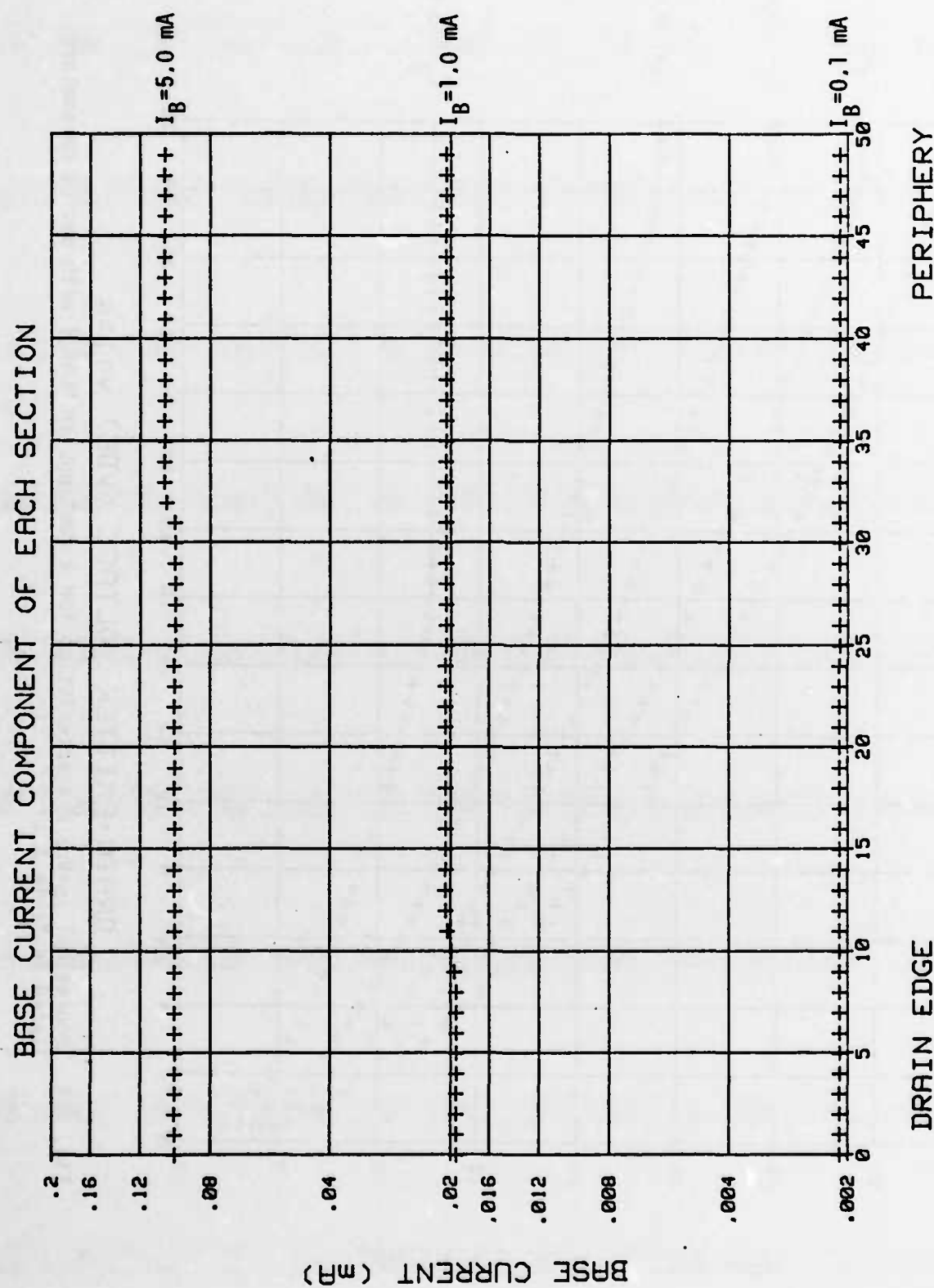


Fig. 3.7 Spatial dependence of channel current ( $I_D$ ) for a rectangular MOSBJT with device parameters listed in Table 3.1.



**Fig. 3.8 Spatial dependence of the sectional base current contribution for a rectangular MOSBJT with device parameters listed in Table 3.1.**

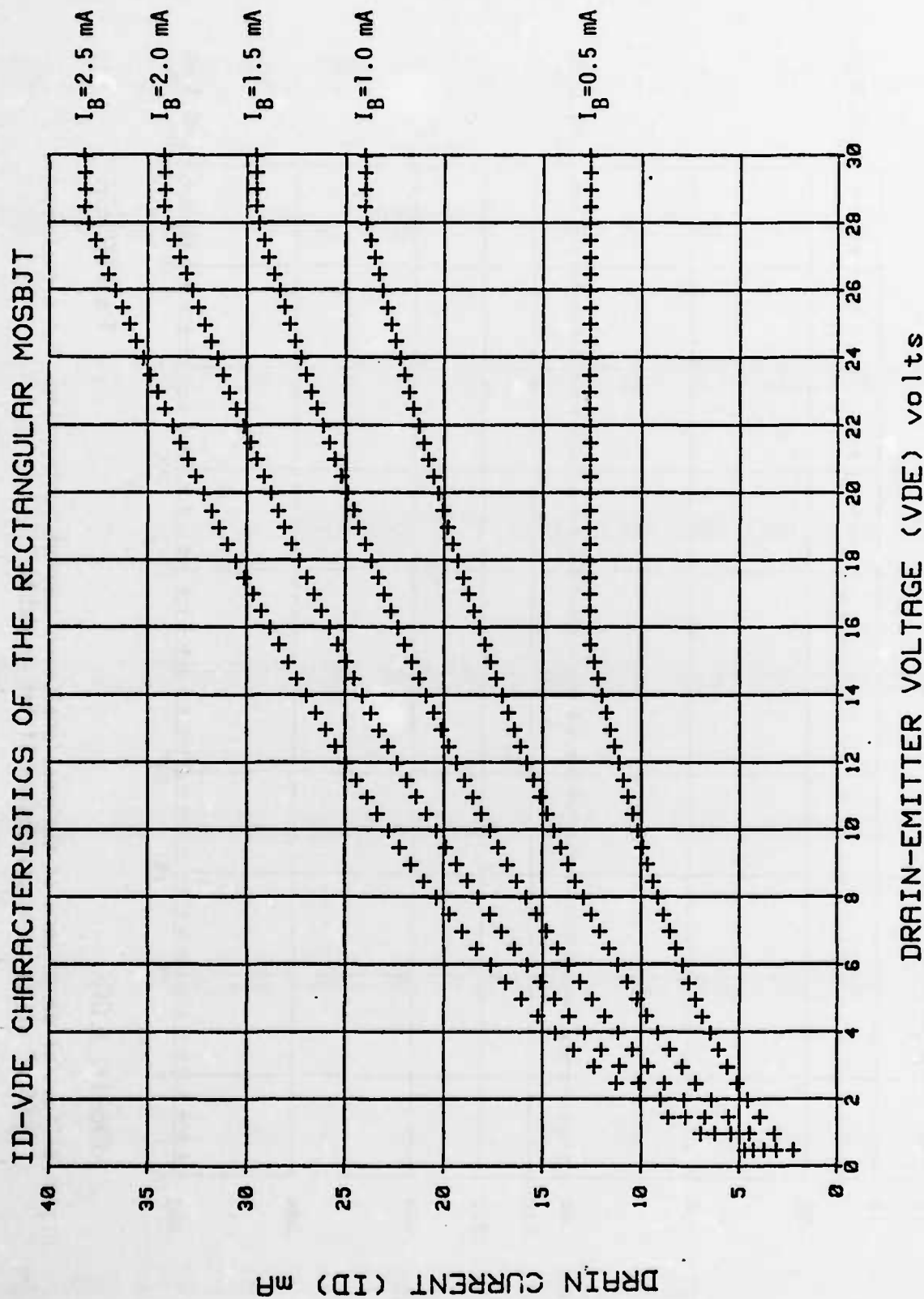


Fig. 3.9 Theoretical  $I_D$ - $V_{DE}$  characteristics for a rectangular MOSBJT with device parameters listed in Table 3.1.

### References Cited

1. D.N. Okada, "Fabrication of a Silicon MOSFET Device with a Bipolar Transistor Source," Masters Thesis, Dec. 1979, University of Hawaii.
2. D.N. Okada, "The MOSBJT Analytical Models." (Unpublished)
3. J.J. Ebers and J.L. Moll, "Large Signal Behavior of Junction Transistors," Proc. IRE, 42, 1761, 1954.
4. R.S. Muller and T.J. Kamins, "Device Electronics for Integrated Circuits," John Wiley & Sons, New York, 1977.



Developed by: David Okada  
Research on the MOSBJT is being directed by  
Dr. James Holm-Kennedy  
University of Hawaii  
Program developed on a HP 9836 with Basic 2.0

## Main Program

I\_V\_char .... Given the operating bias of the MOSBJT  
this program calculates the resultant  
current and and voltage profile along  
the channel and the terminal base and

```

590      drain currents.
600
610      Wid ...      This subprogram to calculate the average
620                    width of a MOSFET circuit element.
630
640      Inca .....   This subprogram calculates the ratio
650                    of the collector area of a particular
660                    section to the total MOSBJT channel area
670
680      *****
690
700
710      SUB I_v_char(Vg,Vde,Vbe,INTEGER N,REAL Ic(*).Im(*),Vd(*).Ibi(*),Ibcal)
720      DIM Vs(200)
730      INTEGER Nmin,Nmax,L
740
750      GOSUB Modulea
760      GOSUB Moduleb
770      GOSUB Modulec
780      GOSUB Moduled
790      GOTO Fini
800
810      !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
820      !                                MODULE A                                !
830      !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
840      !                                1. Define device parameters              !
850      !                                2. Define device geometry                !
860      !                                3. Define material constants             !
870      !                                4. Define device bias                   !
880      !                                5. Calculate necessary intermediate parameters !
890      !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
900
910      Modulea:      !
920                    Define device parameters ....
930
940                    Om - METAL WORK FUNCTION
950                    Os - SILICON WORK FUNCTION
960                    Eox - PERMETIVITY OF SiO2
970                    Es - PERMETIVITY OF Si
980                    Tox - OXIDE THICKNESS
990                    Qss - SURFACE CHARGE DENSITY
1000                   T - TEMPERATURE
1010                   Na - SUBSTRATE DOPING
1020
1030
1040
1050
1060                   Flg=0
1070                   Om=4.10           ! V
1080                   Os=4.9            ! V
1090                   Eox=3.45E-11      ! F/M
1100                   Es=1.04E-10      ! F/M
1110                   Tox=1.2E-7       ! METERS
1120                   T=300             ! DEG K
1130                   Na=1.5E+16        ! CM^-3
1140                   Qss=8.E-5         ! C/M^2
1150
1160
1170                   Define device geometry ...
1180

```

```

1190      Length- LENGTH OF GATE
1200      Width - WIDTH OF GATE
1210      N      - NUMBER OF SECTIONS
1220
1230
1240
1250      Length=3.68E-3      ! METERS
1260      Width=2.96E-3      ! METERS
1270
1280
1290
1300      Specify BJT parameters ...
1310
1320      AF - FORWARD ALPHA
1330      AR - REVERSE ALPHA
1340      IES -
1350      ICS -
1360      XB - BASE WIDTH
1370
1380      Af=.962
1390      Ar=.998
1400      Ies=1.04E-8
1410      Ics=1.002E-8
1420
1430
1440
1450      CALCULATE INTERMEDIATE CONSTANTS
1460
1470      Vfb - FLATBAND VOLTAGE
1480      Vt  - THRESHOLD VOLTAGE
1490      D1  - SECTIONAL MOSFET LENGTH
1500      Cox - OXIDE CAPACITANCE/AREA
1510      Mu  - MOBILITY
1520      Op  - ENERGY DIFFERENCE BETWEEN THE
1530             INTRINSIC AND EXTRINSIC FERMI
1540             LEVELS
1550
1560
1570
1580      Cox=Eox/Tox
1590      Vfb=0m-0s-Qss/Cox
1600      Kb=1.38E-23
1610      Q=1.6E-19
1620      Mu=.05
1630      Ni=1.45E+10
1640      Op=-1*(Kb*T/Q)*LOG(Na/Ni)
1650      D1=Length/N
1660      Vt=Vfb+2*ABS(Op)+(1/Cox)*SQR(2*Es*Q*Na*1.0E+6*(2*ABS(Op)))
1670
1680      IF THE MOSBJT IS BIASED INTO SATURATION VDE>VG-VT THEN VDE IS SET
1690      TO VG-VT
1700
1710      IF Vde>Vg-Vt THEN
1720          Vde=Vg-Vt
1730          PRINT "DEVICE SATURATED VDSAT=VG-VT = ",Vde
1740      END IF
1750
1760
1770      PRINT THE ABOVE DATA
1780

```

```

1790 !
1800 PRINT "OM=",Om
1810 PRINT "OS=",Os
1820 PRINT "EOX=",Eox
1830 PRINT "ES=",Es
1840 PRINT "TOX=",Tox
1850 PRINT "QSS=",Qss
1860 PRINT "T=",T,"K"
1870 PRINT "NA =",Na
1880 PRINT "LENGTH=",Length
1890 PRINT "WIDTH=",Width
1900 PRINT "NUMBER OF SECTIONS IS ",N
1910 PRINT "IES = ",Ies
1920 PRINT "ICS = ",Ics
1930 PRINT "AF = ",Af
1940 PRINT "OP = ",Op
1950 PRINT "VFB = ",Vfb
1960 !
1970 !
1980 RETURN
1990 !
2000 !
2010 !
2020 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2030 !
2040 ! MODULE B
2050 !
2060 ! Determine extent of channel cut-off
2070 !
2080 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2090 !
2100 Moduleb: !
2110 !
2120 ! Vbc .. The channel to emitter bias such that Ic=0
2130 !
2140 ! Vchemin . The channel to emitter bias such that the
2150 ! BJT connected to that node Ic is slightly
2160 ! greater than 0. (Node is biased at the
2170 ! onset of cutoff)
2180 !
2190 ! Lco ... Indicates the current section being
2200 ! examined to determine if it is "active"
2210 !
2220 ! Vbc=-(Kb*T/Q)*LOG(Af*Ies/Ics)
2230 ! Vchemin=Vbc+.01
2240 ! Vs(1)=Vchemin
2250 ! Nmin=1
2260 ! Nmax=N
2270 !
2280 ! Next_try: !
2290 ! Lco=(Nmin+Nmax)/2
2300 ! Ic(Lco)=0
2310 ! Im(Lco-1)=0
2320 ! Vd(Lco)=Vchemin
2330 !
2340 ! Loop1: !
2350 ! FOR L=Lco TO N
2360 ! IF Q+(-Vd(L)+Vbe)/(Kb*T)<-100 THEN GOTO Around1

```

```

2360      Ic(L)=FNInca(Length,Width,N,L)*(Af*Ies*EXP(Q*Vbe/(Kb*T))-Ics*(EXP(
(Q/(Kb*T))*(Vbe-Vd(L)))-1))
2370      GOTO Around2
2380      !
2390 Around1: !
2400      Ic(L)=FNInca(Length,Width,N,L)*Af*Ies*EXP(Q*Vbe/(Kb*T))
2410      !
2420 Around2: !
2430      Im(L)=Im(L-1)+Ic(L)
2440      IF (Vg-Vt+Vd(L))^2-(2*(Vg-Vt)*Vd(L)+Vd(L)^2+(2*Im(L)*D1)/(Mu*FNWid
(Width,Length,N,L)*Cox))<0 THEN GOTO Cut_off
2450      Vd(L+1)=Vg-Vt+Vd(L)-SOR((Vg-Vt+Vd(L))^2-(2*(Vg-Vt)*Vd(L)+Vd(L)^2+(
2*Im(L)*D1)/(Mu*FNWid(Width,Length,N,L)*Cox)))
2460      IF Vd(L+1)>Vde THEN GOTO Cut_off
2470      NEXT L
2480      !
2490      !
2500      Nmax=Lco
2510      IF Nmin=Nmax-1 THEN
2520      FOR L=1 TO Lco-1
2530      Ic(L)=0
2540      Im(L-1)=0
2550      Vd(L)=Vchemin
2560      NEXT L
2570      GOTO Found_it
2580      END IF
2590      GOTO Next_try
2600 Cut_off: !
2610      Nmin=Lco
2620      IF (Lco>=N) THEN
2630          DISP " ERROR !!!!!! ENTIRE CHANNEL IS CUT OFF !"
2640          DISP " RERUN PROGRAM WITH A LARGER N "
2650          BEEP
2660          PAUSE
2670          END IF
2680      GOTO Next_try
2690      !
2700 Found_it: !
2710      RETURN
2720      !
2730      !
2740      !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2750      !
2760      !
2770      !
2780      !
2790      !
2800      !
2810      !
2820      !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2830      !
2840      !
2850      !
2860      !
2870      !
2880      !
2890      !
2900      !
2910      !

```

MODULE C

1. Iterate until Vdcal = Vde
2. Record the spatial dependence of channel voltage and current

```

2940 Modulec:      !
2950      K=1
2960 Loop2:      !
2970      FOR L=Lco TO N
2980      IF Q*(Vbe-Vd(L))/(Kb*T)<-100 THEN GOTO Around3
2990      Ic(L)=FNInca(Length,Width,N,L)*(Af*Ies*EXP(Q*Vbe/(Kb*T))-Ics*(EXP(
Q*(-Vd(L)+Vbe)/(Kb*T))-1))
3000      GOTO Around4
3010 Around3:      !

```

```

2920      Ic(L)=FNInca(Length.Width,N,L)*(Af*Ies*EXP(Q*Vbe/(Kb*T)))
2930 Around4: !
2940      Im(L)=Im(L-1)+Ic(L)
2950      IF (Vg-Vt+Vd(L))^2-(2*(Vg-Vt)*Vd(L)+Vd(L)^2+(2*Im(L)*D1)/(Mu*FNWid
(WIDTH.Length,N,L)*Cox))<0 THEN GOTO Decrease
2960      Vd(L+1)=Vg-Vt+Vd(L)-SQRT((Vg-Vt+Vd(L))^2-(2*(Vg-Vt)*Vd(L)+Vd(L)^2+(
2*Im(L)*D1)/(Mu*FNWid(WIDTH.Length,N,L)*Cox)))
2970      IF Vd(L+1)>Vde THEN GOTO Decrease
2980      NEXT L
2990 Adjust: !
3000 !
3010 !
3020      IF K=1 THEN
3030          Vmin=Vs(K)
3040          Vmax=Vs(K)
3050      END IF
3060      IF Flg=1 THEN GOTO Increase
3070      IF Vd(L+1)-Vde>0 THEN
3080          Flg=1
3090          GOTO Decrease
3100      END IF
3110      Vmin=Vs(K)
3120      Vs(K+1)=SGN(Vd(L+1)-Vde)*(-1.)+Vs(K)
3130      Vd(Lco)=Vs(K+1)
3140      K=K+1
3150      GOTO Loop2
3160 Increase: !
3161      Vdcal=Vd(N+1)
3170      IF ABS(Vdcal-Vde)<.01 THEN GOTO Out
3180      IF SGN(Vdcal-Vde)>0 THEN GOTO Decrease
3190      Vmin=Vs(K)
3200      GOTO New_guess
3210 Decrease: !
3220      Flg=1
3230      Vmax=Vs(K)
3240 New_guess: !
3250      Vs(K+1)=(Vmax+Vmin)/2
3260      K=K+1
3270      Vd(Lco)=Vs(K)
3280      GOTO Loop2
3290 Out: !
3300      RETURN
3310 !
3320 !
3330 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
3340 !
3350 !                                MODULE D
3360 !
3370 !                                CALCULATE IB
3380 !
3390 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
3400 !
3410 Moduled: !
3420      Ibc=0
3430      FOR L=1 TO N
3440          IF ((-Vd(L+1)+Vbe)/(Kb*T))<-50 THEN GOTO Around5
3450          Ib=FNInca(Length.Width,N,L)*(Ies*(1-Af)*(EXP(Q*Vbe/(Kb*T))-1)+(Ics
-Af*Ies)*(EXP(Q*(-Vd(L+1)+Vbe)/(Kb*T))-1))
3460          GOTO 3490
3470 Around5: !

```

```

3480      Ib=FNInca(Length.Width,N,L)*((Ies*(1-Af)*(EXP(Q*Vbe/(Kb*T)))-1)-(Ics
-Af*Ies))
3490      Ibi(L)=Ib
3500      Ibcac=Ibcac+Ib
3510      NEXT L
3520      RETURN
3530      !
3540      Fini:      !
3550      !
3560      SUBEND
3570      !
3580      !
3590      !
3600      DEF FNInca(Length.Width,INTEGER N,INTEGER L)
3610      F=N
3620      Inca=1/F
3630      RETURN Inca
3640      FNEND
3650      !
3660      DEF FNWid(Length.Width,INTEGER N,INTEGER L)
3670      Wid=Width
3680      RETURN Wid
3690      FNEND
3700      !
3710      !

```



**END**

**FILMED**

**9-83**

**DTIC**